


# MATERIAL DECLARATION SHEET



Material Number	BSDW20G65C2 TO247-3			
Product Line	Semiconductor			
Compliance Date	2023-5-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	2.14	Silicon Carbide (SiC)	409-21-2	100	0.029	0.029
2	Die Attach	Die Attach	0.12	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.002	0.031
			2.14	Silver (Ag)	7440-22-4	95	0.029	
3	Lead Frame	Copper alloy	1.46	Phosphorous (P)	7723-14-0	0.03	0.02	66.308
			4.86	Iron (Fe)	7439-89-6	0.1	0.066	
			4849.69	Copper (Cu)	7440-50-8	99.87	66.222	
4	Mold Compound	Resin	97.2	Phenol Formaldehyde resin (generic)	9003-35-4	4	1.327	33.181
			364.5	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	15	4.977	
			1798.2	Silica fused	60676-86-0	74	24.554	
			170.1	Silica-amorphous	7631-86-9	7	2.323	
5	Plating	Tin plating	30	Tin (Sn)	7440-31-5	100	0.41	0.41
6	Wire	Pure metal	2.98	Aluminium (Al)	7429-90-5	100	0.041	0.041
			<b>Total weight</b>	<b>7323.39 mg</b>				

**This Document was updated on:** 2023/5/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements